

February 1994 Revised March 2001

74LCX646

Low Voltage Octal Transceiver/Register with 5V Tolerant Inputs and Outputs

General Description

The LCX646 consists of registered bus transceiver circuits, D-type flip-flops, and control circuitry providing multiplexed transmission of data directly from the input bus or from the internal storage registers. Data on the A or B bus will be loaded into the respective registers on the LOW-to-HIGH transition of the appropriate pin (CPAB or CPBA) (see Functional Description).

The LCX646 is designed for low voltage (2.5V or 3.3V) $\rm V_{CC}$ applications with capability of interfacing to a 5V signal environment.

The LCX646 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V 3.6V V_{CC} specifications provided
- \blacksquare 7.0 ns t_{PD} max (V_{CC} = 3.3V), 10 μ A I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- \pm 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

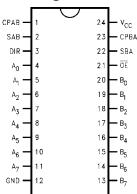
Note 1: To ensure the high-impedance state during power up or down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

Order Number	Package Number	Package Description
74LCX646WM	M24B	24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74LCX646MSA	MSA24	24-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LCX646MTC	MTC24	24-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

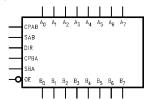
Connection Diagram

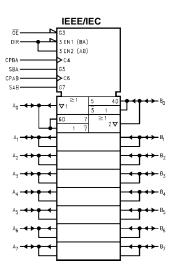


Pin Descriptions

Pin Names	Description
A ₀ -A ₇	Data Register A Inputs
	Data Register A Outputs
B ₀ –B ₇	Data Register B Inputs
	Data Register B Outputs
CPAB, CPBA	Clock Pulse Inputs
SAB, SBA	Transmit/Receive Inputs
ŌĒ	Output Enable Input
DIR	Direction Control Input

Logic Symbols





Truth Table

(Note 2)

	<i>-</i> ,								
Ī			Inp	uts			Data	a I/O	
	OE	DIR	СРАВ	СРВА	SAB	SBA	A ₀ -A ₇	B ₀ -B ₇	Function
Ī	Н	Х	H or L	H or L	Χ	Х			Isolation
	Н	Χ	~	Χ	Χ	Χ	Input	Input	Clock A _n Data into A Register
	Н	Χ	Χ	~	Χ	Χ			Clock B _n Data into B Register
Ī	L	Н	Х	Χ	L	Х			A _n to B _n —Real Time (Transparent Mode)
	L	Н	~	Χ	L	Χ	Input	Output	Clock A _n Data into A Register
	L	Н	H or L	Χ	Н	Χ			A Register to B _n (Stored Mode)
	L	Н	~	Χ	Н	Χ			Clock A _n Data into A Register and Output to B _n
Ī	L	L	Х	Χ	Х	L			B _n to A _n —Real Time (Transparent Mode)
	L	L	Χ	~	Χ	L	Output	Input	Clock B _n Data into B Register
	L	L	Χ	H or L	Χ	Н			B Register to A _n (Stored Mode)
	L	L	Χ	~	X	Н			Clock B _n Data into B Register and Output to A _n

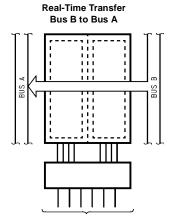
Note 2: The data output functions may be enabled or disabled by various signals at the $\overline{\text{OE}}$ and DIR inputs. Data input functions are always enabled; i.e., data at the bus pins will be stored on every LOW-to-HIGH transition of the appropriate clock inputs.

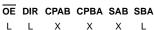
H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
\(\triangle = \text{LOW-to-HIGH Transition}\)

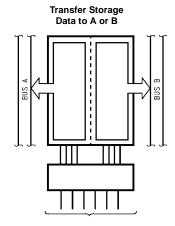
Functional Description

In the transceiver mode, data present at the HIGH impedance port may be stored in either the A or B register or both. The select (SAB, SBA) controls can multiplex stored and real-time. The examples shown below demonstrate the four fundamental bus-management functions that can be performed.

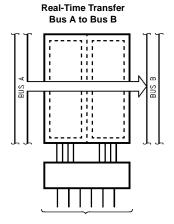
The direction control (DIR) determines which bus will receive data when \overline{OE} is LOW. In the isolation mode (\overline{OE} HIGH), A data may be stored in one register and/or B data may be stored in the other register. When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two busses, A or B, may be driven at a time.





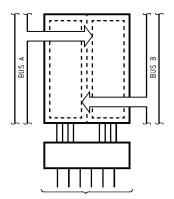


OE	DIR	CPAB	СРВА	SAB	SBA
L	L	X	H or L	Χ	Н
L	н	H or L	Χ	Н	Х



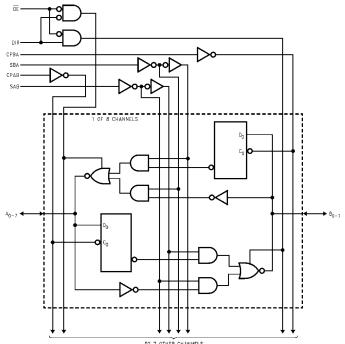


Storage



OE	DIR	CPAB	CPBA	SAB	SBA
L	Н	~	X	L	Χ
L	L	X	~	Χ	L
Н	Χ	~	X	Χ	Χ
Н	X	X	_	X	X

Logic Diagram



TO 7 OTHER CHANNELS

Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 3) Symbol Parameter Value Conditions Units -0.5 to +7.0 ٧ Supply Voltage V_{CC} ٧ DC Input Voltage -0.5 to +7.0 V_{I} DC Output Voltage Output in 3-STATE Vo -0.5 to +7.0 ٧ Output in HIGH or LOW State (Note 4) -0.5 to $V_{CC} + 0.5$ DC Input Diode Current -50 V_I < GND mΑ I_{IK} DC Output Diode Current -50 V_O < GND mΑ +50 $V_O > V_{CC}$ DC Output Source/Sink Current ±50 mΑ lο I_{CC} DC Supply Current per Supply Pin ±100 mΑ DC Ground Current per Ground Pin ±100 mΑ I_{GND} Storage Temperature -65 to +150 °C $\mathsf{T}_{\mathsf{STG}}$

Recommended Operating Conditions (Note 5)

Symbol	Parameter		Min	Max	Units
V _{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
VI	Input Voltage		0	5.5	V
V _O	Output Voltage	HIGH or LOW State	0	V _{CC}	V
		3-STATE	0	5.5	V
I _{OH} /I _{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		±24	
		$V_{CC} = 2.7V - 3.0V$ $V_{CC} = 2.3V - 2.7V$		±12	mA
		$V_{CC} = 2.3V - 2.7V$		±8	
T _A	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, $V_{IN} = 0.8V - 2.0V$, $V_{CC} = 3.0V$		0	10	ns/V

Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 4: I_O Absolute Maximum Rating must be observed.

Note 5: Unused inputs or I/Os must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Cumbal	Parameter	Conditions	V _{CC}	$T_A = -40^{\circ}C$	Units	
Symbol		Conditions	(V)	Min	Max	Units
V _{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		ľ
/ _{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 - 3.6		8.0	İ v
/ _{ОН}	HIGH Level Output Voltage	$I_{OH} = -100 \mu\text{A}$	2.3 – 3.6	V _{CC} - 0.2		
		$I_{OH} = -8 \text{ mA}$	2.3	1.8		Ì
		$I_{OH} = -12 \text{ mA}$	2.7	2.2		٧
		$I_{OH} = -18 \text{ mA}$	3.0	2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.2		İ
V _{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.3 – 3.6		0.2	
		$I_{OL} = 8 \text{ mA}$	2.3		0.6	İ
		I _{OL} = 12 mA	2.7		0.4	٧
		I _{OL} = 16 mA	3.0		0.4	İ
		I _{OL} = 24 mA	3.0		0.55	İ
I	Input Leakage Current	$0 \le V_1 \le 5.5V$	2.3 – 3.6		±5.0	μΑ
OZ	3-STATE I/O Leakage	$0 \le V_O \le 5.5V$	2.3 – 3.6		±5.0	^
		$V_I = V_{IH}$ or V_{IL}	2.3 – 3.6		±3.0	μА
OFF	Power-Off Leakage Current	V _I or V _O = 5.5V	0		10	μΑ

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units
Cymbol	Talameter Condition	Conditions	(V)	Min	Max	Onito
I _{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.3 – 3.6		10	uА
		3.6V ≤ V _I , V _O ≤ 5.5V (Note 6)	2.3 – 3.6		±10	μΛ
ΔI_{CC}	Increase in I _{CC} per Input	$V_{IH} = V_{CC} - 0.6V$	2.3 – 3.6		500	μΑ

Note 6: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

			$T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $R_L = 500\Omega$					
0	Parameter	V _{CC} = 3.	3V ± 0.3V	v _{cc}	= 2.7V	V _{CC} = 2.	.5V ± 0.2V	Units
Symbol	Farameter	C _L =	C _L = 50 pF		C _L = 50 pF		C _L = 30 pF	
		Min	Max	Min	Max	Min	Max	
f _{MAX}	Maximum Clock Frequency	150						MHz
t _{PHL}	Propagation Delay	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{PLH}	Bus to Bus	1.5	7.0	1.5	8.0	1.5	8.4	115
t _{PHL}	Propagation Delay	1.5	8.5	1.5	9.5	1.5	10.5	
t _{PLH}	Clock to Bus	1.5	8.5	1.5	9.5	1.5	10.5	ns
t _{PHL}	Propagation Delay	1.5	8.5	1.5	9.5	1.5	10.5	
t _{PLH}	Select to Bus	1.5	8.5	1.5	9.5	1.5	10.5	ns
t _{PZL}	Output Enable Time	1.5	8.5	1.5	9.5	1.5	10.5	ns
t _{PZH}		1.5	8.5	1.5	9.5	1.5	10.5	115
t _{PLZ}	Output Disable Time	1.5	8.5	1.5	9.5	1.5	10.5	
t _{PHZ}		1.5	8.5	1.5	9.5	1.5	10.5	ns
ts	Setup Time	2.5		2.5		4.0		ns
t _H	Hold Time	1.5		1.5		2.0		ns
t _W	Pulse Width	3.3		3.3		4.0		ns
toshl	Output to Output Skew		1.0					ns
t _{OSLH}	(Note 7)		1.0					115

Note 7: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	v _{cc}	$T_A = 25^{\circ}C$	Units
Cymbol	rarameter	Conditions	(V)	Typical	Oilles
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	0.8	V
		$C_L = 30 \text{ pF, } V_{IH} = 2.5 \text{V, } V_{IL} = 0 \text{V}$	2.5	0.6	v
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.8	V
İ		$C_L = 30 \text{ pF, } V_{IH} = 2.5 \text{V, } V_{IL} = 0 \text{V}$	2.5	-0.6	V

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$	7	pF
C _{I/O}	Input/Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_{I} = 0V$ or V_{CC} , $f = 10$ MHz	25	pF

AC LOADING and WAVEFORMS Generic for LCX Family

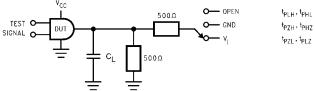
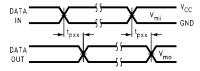
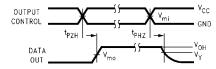


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

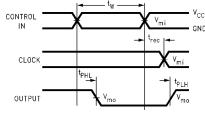
Test	Switch
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at V_{CC} = 3.3 \pm 0.3V V_{CC} x 2 at V_{CC} = 2.5 \pm 0.2V
t _{PZH} ,t _{PHZ}	GND



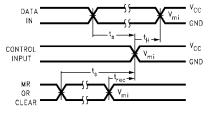
Waveform for Inverting and Non-Inverting Functions



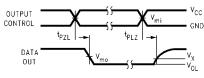
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

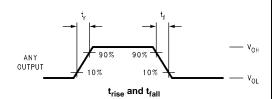
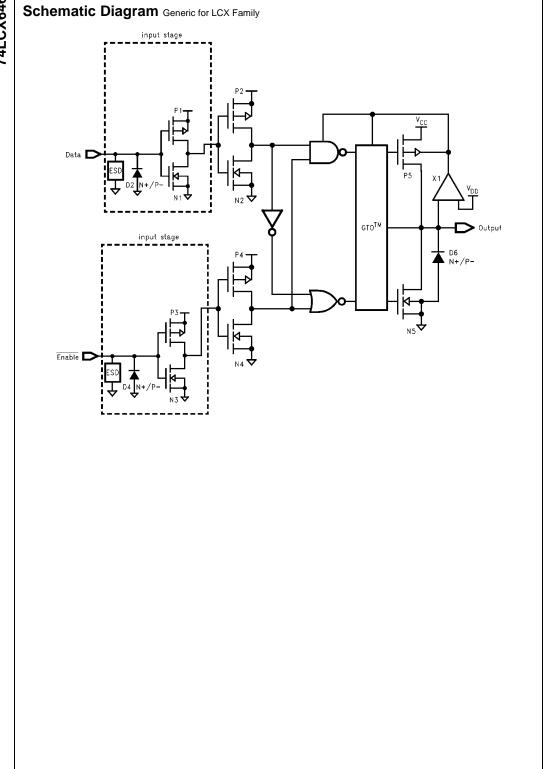
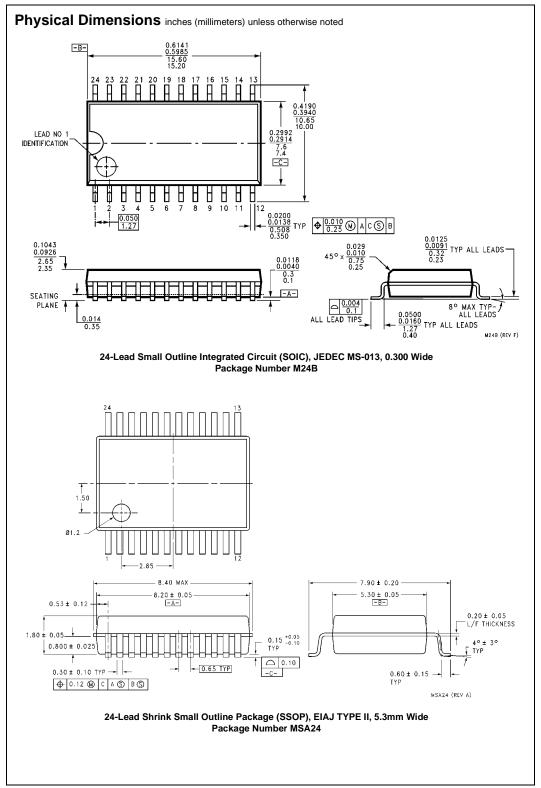
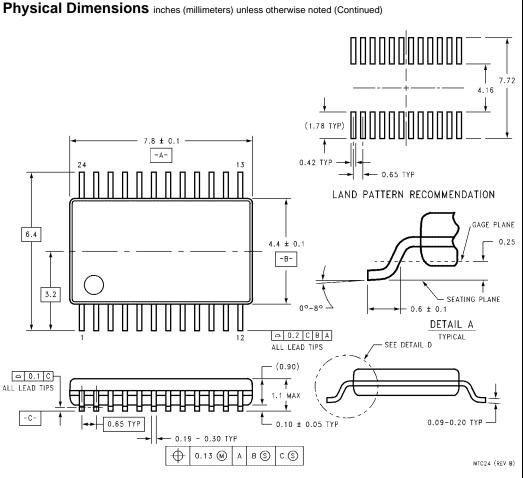


FIGURE 2. Waveforms (Input Characteristics; f = 1 MHz, $t_r = t_f = 3 \text{ns}$)

Symbol	V _{cc}		
	$3.3V \pm 0.3V$	2.7V	2.5V ± 0.2V
V _{mi}	1.5V	1.5V	V _{CC} /2
V_{mo}	1.5V	1.5V	V _{CC} /2
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	V _{OL} + 0.15V
V _y	V _{OH} – 0.3V	V _{OH} – 0.3V	V _{OH} – 0.15V







24-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC24

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